

ABSTRACT

A semiconductor element with electrodes, and a passive element with electrodes are embedded in a thermoplastic sheet base, which is then subjected to laser beam machining, electron beam machining or ion beam machining to expose electrodes. Thereafter, a circuit pattern is formed by formation of a thin film or printing of a conductive adhesive. Because of exposing the electrodes by laser beam machining or the like manner as above, the exposure can be carried out in a short period of time and also by a local treatment, thereby reducing damages to the base. The high-quality, high-productivity and inexpensive manufacturing method for electronic component-mounted components, manufacturing method for electronic component-mounted completed products, and electronic component-mounted completed products can be provided accordingly.